



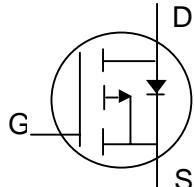
## P-channel Enhancement-mode Power MOSFET

**Simple Drive Requirement**

**Good Thermal Performance**

**Low On-resistance**

**RoHS-compliant, halogen-free**

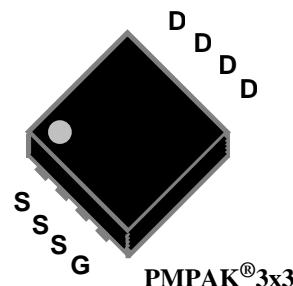


$BV_{DSS}$	-30V
$R_{DS(ON)}$	14.5mΩ
$I_D$	-13.1A

## Description

Advanced Power MOSFETs from APEC provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The PMPAK®3x3 package is specially designed for DC-DC converter applications, with a small foot print that offers a backside heat sink and a low package profile.



## Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	-30	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D$ at $T_A=25^\circ C$	Continuous Drain Current <sup>3</sup>	-13.1	A
$I_D$ at $T_A=70^\circ C$	Continuous Drain Current <sup>3</sup>	-10.5	A
$I_{DM}$	Pulsed Drain Current <sup>1</sup>	-50	A
$P_D$ at $T_A=25^\circ C$	Total Power Dissipation	3.57	W
$T_{STG}$	Storage Temperature Range	-55 to 150	°C
$T_J$	Operating Junction Temperature Range	-55 to 150	°C

## Thermal Data

Symbol	Parameter	Value	Units
$R_{thj-c}$	Maximum Thermal Resistance, Junction-case	5	°C/W
$R_{thj-a}$	Maximum Thermal Resistance, Junction-ambient <sup>3</sup>	35	°C/W

## Ordering Information

**AP4451GYT-HF-3TR**

**RoHS-compliant halogen-free PMPAK®3x3, shipped on tape and reel (3000pcs/reel)**

PMPAK® is a registered trademark of Advanced Power Electronics Corp.





## Typical Electrical Characteristics

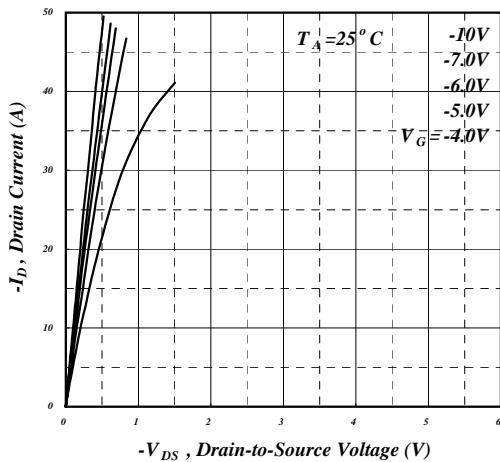


Fig 1. Typical Output Characteristics

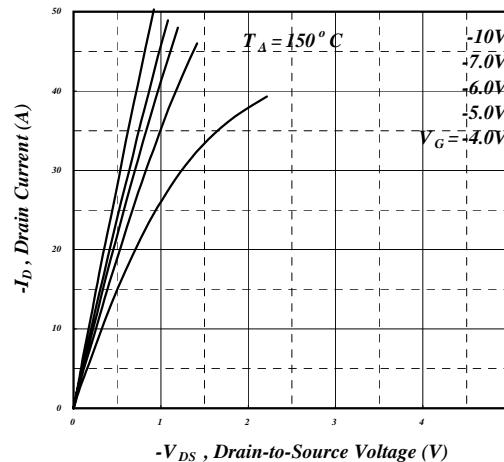


Fig 2. Typical Output Characteristics

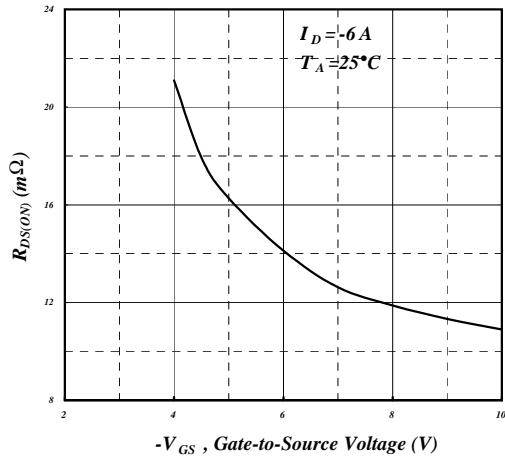


Fig 3. On-Resistance vs. Gate Voltage

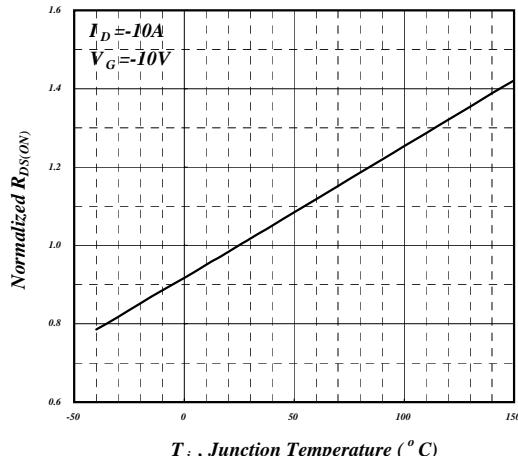


Fig 4. Normalized On-Resistance vs. Junction Temperature

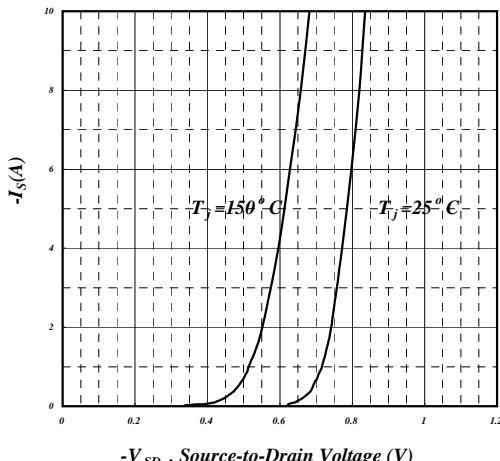


Fig 5. Forward Characteristic of Reverse Diode

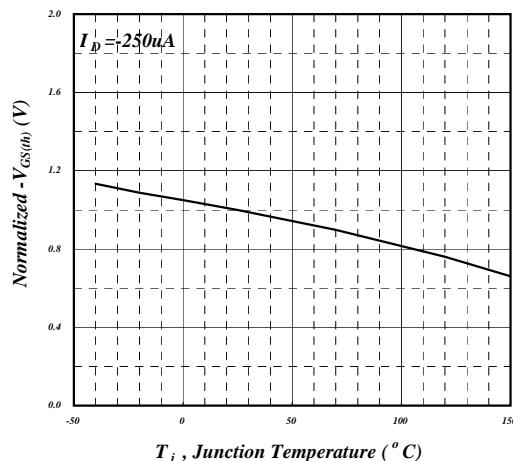


Fig 6. Gate Threshold Voltage vs. Junction Temperature



## Typical Electrical Characteristics (cont.)

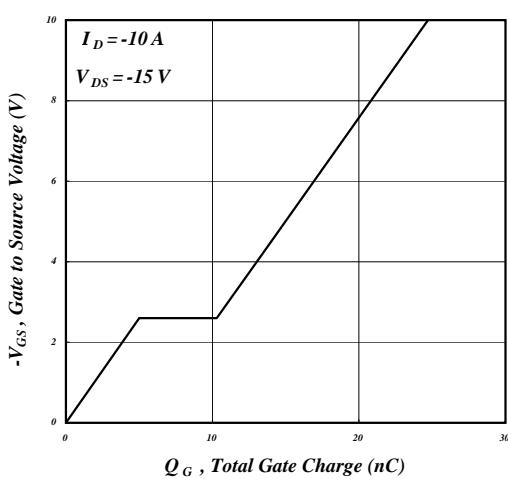


Fig 7. Gate Charge Characteristics

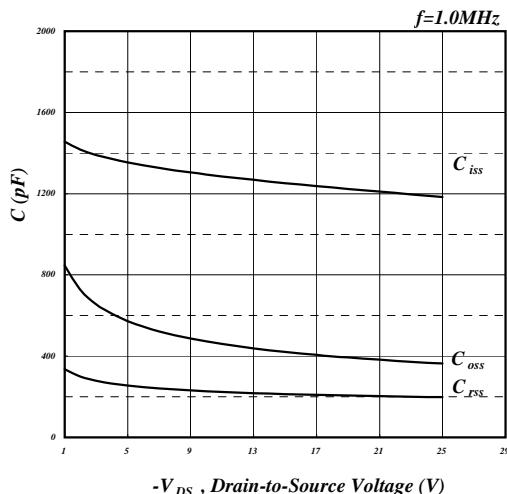


Fig 8. Typical Capacitance Characteristics

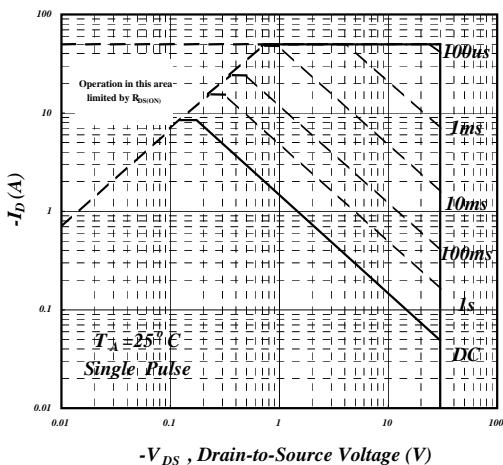


Fig 9. Maximum Safe Operating Area

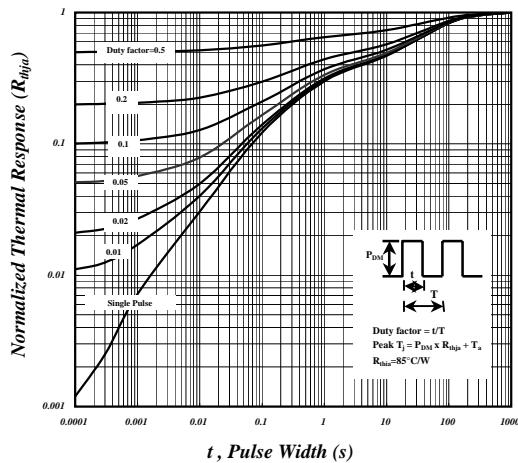


Fig 10. Effective Transient Thermal Impedance

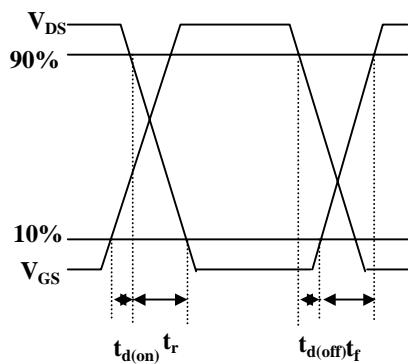


Fig 11. Switching Time Waveforms

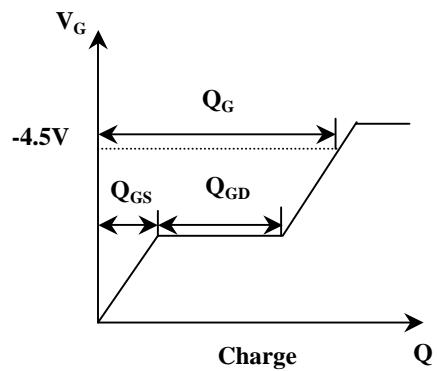
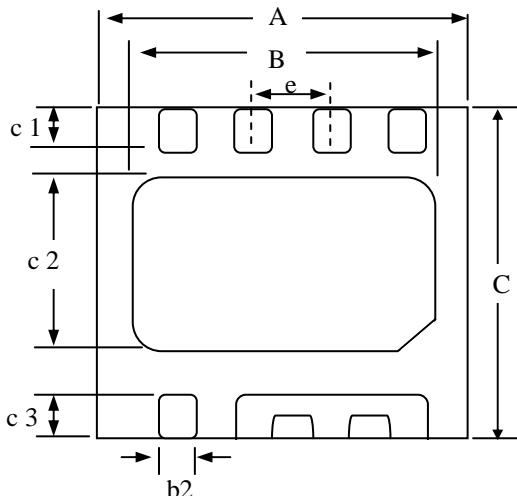


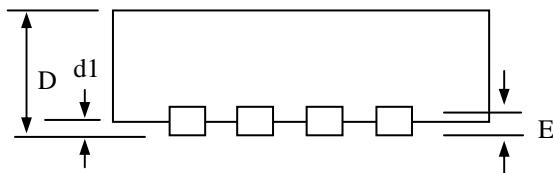
Fig 12. Gate Charge Waveform



## Package Dimensions: PMPAK®3x3



SYMBOLS	Millimeters		
	MIN	NOM	MAX
A	2.95	3.00	3.05
B	2.35	2.40	2.45
e	0.65 (ref.)		
b2	0.30	0.35	0.40
C	2.95	3.00	3.05
c1	0.37	0.42	0.47
c2	1.65	1.70	1.75
c3	0.37	0.42	0.47
D	0.80	0.85	0.95
d1	0.00	-	0.05
E	0.178	0.203	0.228



1. All dimensions are in millimeters.
2. Dimensions do not include mold protrusions.

## Marking Information:

